

## **Amendment to Claims**

1-22 canceled

23 (new): A moisture curable hot melt adhesive composition comprising polyurethane prepolymers prepared by reacting a polyisocyanate with a urethane diol, said urethane diol being the reaction product of a cyclic carbonate and a compound containing an amino group and a further group selected from the group consisting of amino groups and hydroxyl groups.

24 (new): The composition of claim 23 wherein the said compound is a diamine, an alkanolamine, an amine terminated polyamide or mixture thereof.

25 (new): The composition of claim 24 wherein said compound is selected from the group consisting of ethylene diamine, 1,4 butane diamine, 1,6 hexane diamine, 2 methyl 1,5 pentane diamine, 2,2,4 trimethyl-1,6 hexane diamine, 2,4,4 trimethyl-1,6 hexane diamine, polyoxypropylene diamines, ethanolamine, propanolamine and mixtures thereof.

26 (new): The composition of claim 23 wherein said cyclic carbonate is selected from the groups consisting of glycerol carbonate, ethylene carbonate, propylene carbonate and butylene carbonate.

27 (new): The composition of claim 23 wherein the polyurethane prepolymer is prepared by reacting said polyisocyanate with a urethane diol in the presence of a polyether polyol, a polyester polyol, a (meth)acrylic polymer, thermoplastic polymer, tackifying resin or mixture thereof.

28 (new): The composition of claim 23 which is in solid form.

29 (new): The composition of claim 23 which is in liquid form.

30 (new): The composition of claim 23 wherein the urethane diol is made in situ during the preparation of the polyurethane prepolymers.

31 (new): The composition of claim 29 which has a melt viscosity suitable to enable application at a temperature of less than 100°C.

32 (new): A method of bonding materials together which comprises applying the moisture curable hot melt adhesive composition of claim 23 in a liquid form to a first substrate, bringing a second substrate in contact with the composition applied to the first substrate, and subjecting the composition to conditions which will allow the compositions to cool and cure to an irreversible solid form, the conditions comprising moisture.

33 (new): The method of claim 32 wherein the adhesive composition in liquid form is applied at a temperature of less than 100°C.

34 (new): The method of claim 32 wherein the adhesive composition in liquid form is applied at a temperature of 90°C to 100°C.

35 (new): An article of manufacture which comprises the composition of claim 23 which composition has been cured by exposure to moisture.